TGn Sync, WWiSE and Mitmot closing report

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Abstract

- This document provides an update on the joint proposal effort this week among TGn Sync, WWiSE, and Mitmot

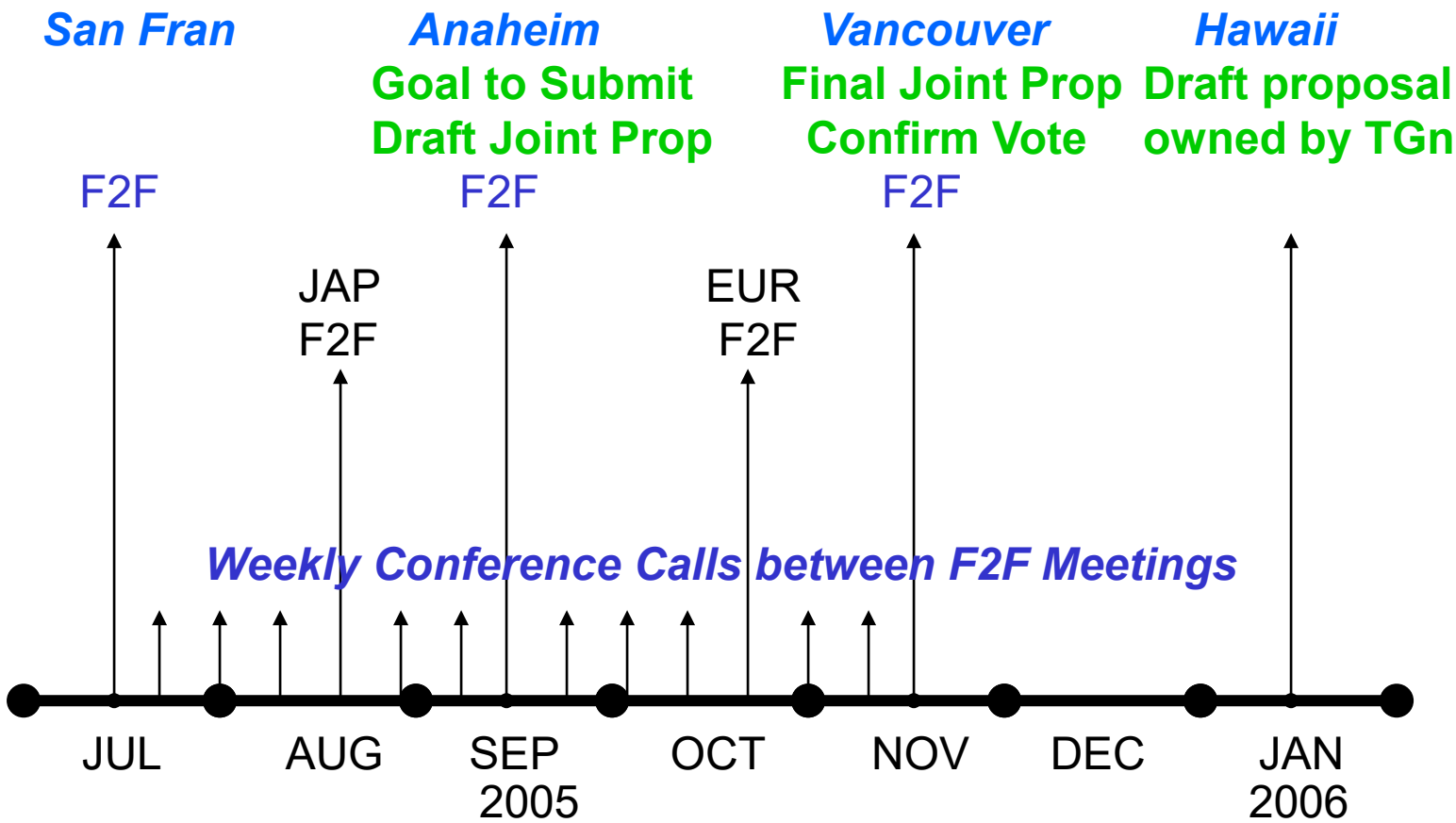
Procedural Updates

- Adopted a process for creating the joint proposal
  - Adopted a decision making procedure
  - Agreed on web tools to help facilitate document sharing and conference calls
- Established a firm and aggressive schedule for F2F and conference calls

PHY/MAC Teams Update

- Created a sequence of discussion points
- Discussed motions for adding draft text to the joint proposal
- Fielded detailed technical presentations on topics of mutual interest
- Created tiger teams to accelerate technical progress

Next Steps

- Weekly conference calls, starting next week
  - One for the MAC, one for the PHY
- F2F meeting in Japan in August
- Will upload one week prior to IEEE in Anaheim either a draft joint proposal or a progress report

Joint Proposal Timeline